

ABSTRACT

Paddleless Molded Plastic Semiconductor Chip Package

A semiconductor package and method in which a semiconductor chip is mounted within an opening of a lead frame by bonding wires extending between an active front side of the chip and bonding pads of the lead frame; the lead frame/chip assembly is encased within a plastic molded body, with an inactive back surface of the semiconductor chip exposed and facing outside the package.

Figure 9.

This Sheet Has Been Replaced



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